Filename: PMP4586 REV_B_bom.xls
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PMP4586 REV_B BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR	AREA
2	C1	220pF	Capacitor, Ceramic, 50V, NPO, 5%	0603	std	std	
2	C2	0.22uF	Capacitor, Ceramic, 16V, X7R, 10%	0603	std	std	
2	C3	56pF	Capacitor, Ceramic, 50V, NPO, [tol]	0603	std	std	
1	C4	1nF	Capacitor, Ceramic, 50V, X7R [tol]	0603	std	std	
2	C5	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	std	std	
2	C7	1uF	Capacitor, Ceramic, 16V, X7R, 20%	0603	std	std	
4	C8	4.7uF	Capacitor, Ceramic, 50V, X7R, 20%	1210	C3225X7R1H475M	TDK	
2	C9	100pF	Capacitor, Ceramic, 50V, NPO, [tol]	0603	std	std	
	C10	4.7uF	Capacitor, Ceramic, 50V, X7R, 20%	1210	C3225X7R1H475M	TDK	
1	C11	100uF	Capacitor, Aluminum, 50V, 0.22 Ohm @-20^C ZL series	0.315 inch	xxxZLxxxxxxxxxxxxx	Rubycon	
2	C12	10uF	Capacitor, Ceramic, 25V, X7R, 10%	1210	C3225X5R1E106K	TDK	
2	C15	4.7uF	Capacitor, Ceramic, 4.7uF, 50V, X7R, 20%	1210	C3225X7R1H475M	TDK	
2	C27	OPEN	Capacitor, Aluminum, 220uF, 50V, 0.042 Ohms	0.315	050ZL220uF20%10X16	Rubycon	
	C10BIS10	4.7uF	Capacitor, Ceramic, 50V, X7R, 20%	1210	C3225X7R1H475M	TDK	
1	C11BIS11	100uF	Capacitor, Aluminum, vvV, [temp], [tol]	0.315 inch	xxxZLxxxxxxxxxxxxx	Rubycon	
	C12BIS12	10uF	Capacitor, Ceramic, 25V, X7R, 10%	1210	C3225X5R1E106K	TDK	
	C15BIS15	4.7uF	Capacitor, Ceramic, 4.7uF, 50V, X7R, 20%	1210	C3225X7R1H475M	TDK	
	C1BIS1	220pF	Capacitor, Ceramic, 50V, NPO, 5%	0603	std	std	
	C27BIS27	OPEN	Capacitor, Aluminum, 220uF, 50V, 0.042 Ohms	0.315	050ZL220uF20%10X16	Rubycon	
	C2BIS2	0.22uF	Capacitor, Ceramic, 16V, X7R, 10%	0603	std	std	
	C3BIS3	56pF	Capacitor, Ceramic, 50V, NPO, [tol]	0603	std	std	
1	C4BIS7	1.5nF	Capacitor, Ceramic, 50V, X7R [tol]	0603	std	std	
	C5BIS5	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	std	std	
	C7BIS7	1uF	Capacitor, Ceramic, 16V, X7R, 20%	0603	std	std	
	C8BIS8	4.7uF	Capacitor, Ceramic, 50V, X7R, 20%	1210	C3225X7R1H475M	TDK	
	C9BIS9	100pF	Capacitor, Ceramic, 50V, NPO, [tol]	0603	std	std	
2	D1	MBRS1100T3	Diode, Rectifier, 1-A, 100-V	SMB	STD	STD	
2	D2	27V	Diode, Zener, 27-V, 225-mW, 5%	SOT23	MMBZ5254BLT1G	On Semi	
2	D102	BAT54	Diode, Schottky, 200-mA, 30-V	SOT23	BAT54	Vishay-Liteon	
	D102BIS10	BAT54	Diode, Schottky, 200-mA, 30-V	SOT23	BAT54	Vishay-Liteon	
	D1BIS1	MBRS1100T3	Diode, Rectifier, 1-A, 100-V	SMB	STD	STD	
	D2BIS2	27V	Diode, Zener, 27-V, 225-mW, 5%	SOT23	MMBZ5254BLT1G	On Semi	
4	J1	D120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	D120/2DS	OST	
	J2	D120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	D120/2DS	OST	
2	J3	PTC36SAAN	Header, 3-pin, 100mil spacing, (36-pin strip)	0.100 inch x 3	std	std	
	J1BIS1	D120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	D120/2DS	OST	
	J2BIS2	D120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	D120/2DS	OST	
	J3BIS3	PTC36SAAN	Header, 3-pin, 100mil spacing, (36-pin strip)	0.100 inch x 3	std	std	
2	L2	68uH	Inductor, SMT, 4.1A, 1.35A each, 105milliohm	0.484 x 0.484 in	MSD1278 -683MLD	Coilcraft	
2	L4	Short	Inductor, SMT, yyA, zzmilliohm	0.200 x 0.200 in	DNP	DNP	
	L2BIS2	68uH	Inductor, SMT, 4.1A, 1.35A each, 105milliohm	0.484 x 0.484 in	MSD1278 -683MLD	Coilcraft	
	L4BIS4	Short	Inductor, SMT, yyA, zzmilliohm	0.200 x 0.200 in	DNP	DNP	
2	Q3	FDS3590	MOSFET, N-ch, 80-V, 6.5A, 39mOhm, Qg=25nC	SO8	STD	Fairchild	
	Q3BIS3	FDS3590	MOSFET, N-ch, 80-V, 6.5A, 39mOhm, Qg=25nC	SO8	STD	Fairchild	

4	R1	249k	Resistor, Chip, 1/16W, 1%	0603	std	std
1	R2	475k	Resistor, Chip, 1/16W, 1%	0603	std	std
2	R3	OPEN	Resistor, Chip, 1/16W, 1%	0603	std	std
2	R5	49.9k	Resistor, Chip, 1/16W, 1%	0603	std	std
4	R6	0	Resistor, Chip, 1/16W, 1%	0603	std	std
2	R7	5	Resistor, Chip, 1/16W, 1%	0603	std	std
2	R9	49.9	Resistor, Chip, 1/16W, 1%	0603	std	std
2	R10	1k	Resistor, Chip, 1/16W, 1%	0603	std	std
2	R11	0.06	Resistor, Metal Film, 1/4 watt, ± 5%	1206	Std	Std
	R13	0	Resistor, Chip, 1/16W, 1%	0603	std	std
1	R14	0.75	Resistor, Chip, 1/10W, 1%	0805	CRCW0805-xxxx-F	Vishay
	R105	249K	Resistor, Chip, 1/16W, 1%	0603	std	std
	R105BIS10	249K	Resistor, Chip, 1/16W, 1%	0603	std	std
	R10BIS10	1k	Resistor, Chip, 1/16W, 1%	0603	std	std
	R11BIS11	0.06	Resistor, Metal Film, 1/4 watt, ± 5%	1206	Std	Std
	R13BIS13	0	Resistor, Chip, 1/16W, 1%	0603	std	std
1	R14BIS14	1	Resistor, Chip, 1/10W, 1%	0805	CRCW0805-xxxx-F	Vishay
	R1BIS1	249k	Resistor, Chip, 1/16W, 1%	0603	std	std
1	R2BIS1	400k	Resistor, Chip, 1/16W, 1%	0603	std	std
	R3BIS3	OPEN	Resistor, Chip, 1/16W, 1%	0603	std	std
	R5BIS5	49.9k	Resistor, Chip, 1/16W, 1%	0603	std	std
	R6BIS6	0	Resistor, Chip, 1/16W, 1%	0603	std	std
	R7BIS7	5	Resistor, Chip, 1/16W, 1%	0603	std	std
	R9BIS9	49.9	Resistor, Chip, 1/16W, 1%	0603	std	std
6	TP1	5011	Test Point, Black, Thru Hole	0.125 x 0.125 ir	5011	Keystone
4	TP2	5010	Test Point, Red, Thru Hole	0.125 x 0.125 ir	5010	Keystone
4	TP4	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 ir	5002	Keystone
	TP5	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 ir	5002	Keystone
2	TP7	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 ir	5000	Keystone
	TP8	5011	Test Point, Black, Thru Hole	0.125 x 0.125 ir	5011	Keystone
	TP10	5010	Test Point, Red, Thru Hole	0.125 x 0.125 ir	5010	Keystone
	TP11	5011	Test Point, Black, Thru Hole	0.125 x 0.125 ir	5011	Keystone
	TP10BIS10	5010	Test Point, Red, Thru Hole	0.125 x 0.125 ir	5010	Keystone
	TP11BIS11	5011	Test Point, Black, Thru Hole	0.125 x 0.125 ir	5011	Keystone
	TP1BIS1	5011	Test Point, Black, Thru Hole	0.125 x 0.125 ir	5011	Keystone
	TP2BIS2	5010	Test Point, Red, Thru Hole	0.125 x 0.125 ir	5010	Keystone
	TP4BIS4	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 ir	5002	Keystone
	TP5BIS5	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 ir	5002	Keystone
	TP7BIS7	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 ir	5000	Keystone
	TP8BIS8	5011	Test Point, Black, Thru Hole	0.125 x 0.125 ir	5011	Keystone
2	U1	TPS40211DGS	IC, Low Cost Non-Synchronous Boost Controller	DGS10	TPS40210DGS	TI
	U2	TPS40211DGS	IC, Low Cost Non-Synchronous Boost Controller	DGS10	TPS40210DGS	TI

Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
2. These assemblies must be clean and free from flux and all contaminants.
   Use of no clean flux is not acceptable.
3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
4. Ref designators marked with an asterisk ('**') cannot be substituted.
   All other components can be substituted with equivalent MFG's components.

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